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Research and Progress of High Strength Low Temperature Solders

（Fitech FL170/FL180/FL200）

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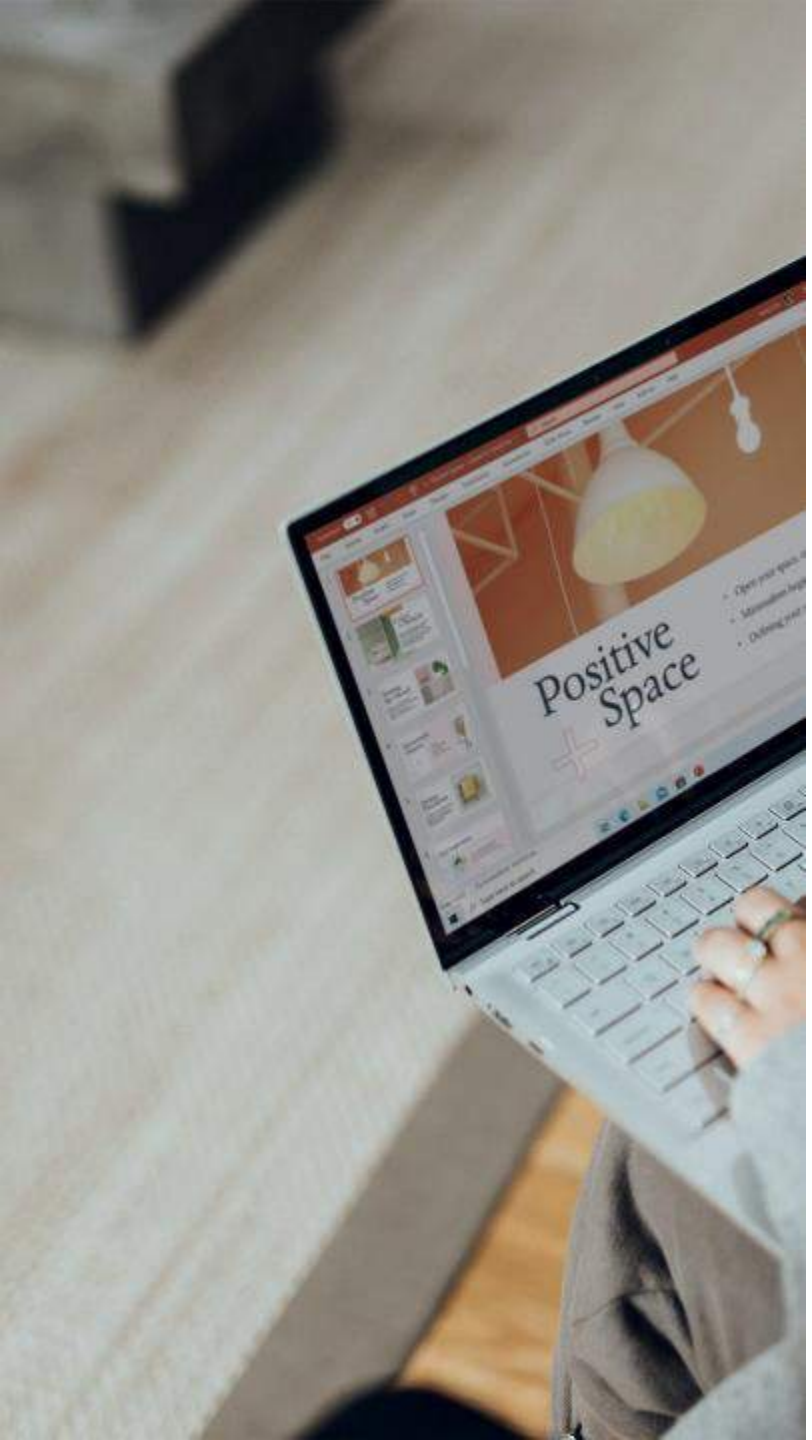

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Objective Review

01- Low-Temperature Solder Market Demand

Anti-Warping Requirements

The development of light, thin, soft and small electronic devices and the market demand for thin substrates and non-temperature-resistant devices require high reliable solder products. SAC solder may lead to many problems like warpage. To handle these problems, low-temperature solder is produced.

Secondary Reflow Process Requirements

At present, the development of high-temperature lead-free solder has reached bottleneck. Since the secondary reflow easily leads to unexpected solder melting, the market needs a solder with a suitable melting temperature for second package process.

Environmental Demand

The global environment and resources are challenged: Solder development has shifted from the leaded to the lead-free era. Tin consumption has risen by more than 40%, and packaging temperatures have increased by 40℃.